

**IN THE CLAIMS:****AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

1. (currently amended) An electroplating solution for plating tin-copper alloy solder coatings comprising:

a sulfonic acid electrolyte;

a tin compound soluble in the sulfonic acid to form a tin sulfonate;

a copper compound soluble in the sulfonic acid to form a copper sulfonate;

a non-ionic surfactant;

a satin brightener comprising ~~an aromatic amine~~, a tertiary amine, or oxidized 1-phenyl-3-pyrazolidinone; and

an antioxidant.

2. (currently amended) The electroplating solution of claim 1 wherein the sulfonic acid electrolyte comprises an alkane or alkanol sulfonic acid containing 1-5 carbon atoms.

3. (original) The electroplating solution of claim 1 wherein the sulfonic acid electrolyte comprises methanesulfonic acid.

4. (original) The electroplating solution of claim 1 wherein the tin compound comprises tin methanesulfonate.

5. (original) The electroplating solution of claim 1 wherein the copper compound comprises copper methanesulfonate.

6. (currently amended) The electroplating solution of claim 1 wherein the non-ionic non-ionic surfactant comprises a polyethylene glycol.

7. (previously presented) The electroplating solution of claim 1 wherein the non-ionic surfactant comprises polyoxyethylene-block-polyoxypropylene with molecular weight between 2000 and 10,000.

Claims 8-9 (canceled)

10. (original) The electroplating solution of claim 1 wherein the antioxidant comprises a catechol.